N	Janufacturer : Anshan Ke	ifat Electronic Ceramic Tec	chnical Co.,Ltd. N	0:	
	Approval	Sheet for Pr	oduct Speci	fication	
(Customer:				
•	Justomei .				
F	Product: Epoxy Mol	lding SMD 250VAC-	·Y1 cap		
F	PART No.:				
N	Mfr. P/N:				
		ı 🗀			
L	Date: 年 月 「				
	Manuf	facturer	Customer	Confirm	
	Prepared by	薛志豪	合格 OK □ 不合格 NG □		
	Checked by	于金龙	Checked by		
	Checken by	1 並ル	Checken by		

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范垂旭

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Approved by

Approved by



	PART NO.	
From Molding CMD 250VAC_V1 con	Edition	Page
Epoxy Molding SMD 250VAC-Y1 cap	Α	2

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	curve	
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13	Caution	



Molding SM	D 250VAC-V1 con		
norum om	D ZOUVACETT CAD	Edition	Page
	Epoxy Molding SMD 250VAC-Y1 cap		3
	Revision History		
Date	Contents of formulation / modification / repeal	Formulation	Approval
	New edition released	薛志豪	于金龙
	Date	repeal	repeal



	PART NO.	
Energy Molding CMD SEOVAC VI con	Edition	Page
Epoxy Molding SMD 250VAC-Y1 cap	Α	4

- 1. Features
- 2. We design capacitors much more compact in thickness than traditional radial Type, having reduced the thickness to 2.5mm height.
- 3. Operating temperature range guaranteed up to 125 degrees C.
- 4. Dielectric strength: AC4000V
- 5. Class X1/Y1capacitors certified by UL/ VDE /ENEC/KC
- 6. Coated with flame retardant epoxy resin (conforming to UL94V 0 standard). We recommend a halogen free & beryllium free product* as our standard item.
 - * CI =900ppm max., Br=900ppm max. and CI+Br=1500ppm max.
- 7. Taping available for automatic SMT reflow.
- 8. AC250V Rated Voltage item are available.
- 9. This one is MSL 3 product. So, in order to avoid the absorption of moisture, capacitors are packed in moisture-proof envelope.

Store the capacitors in the following conditions at all times, and use within 6 months after delivered.

Temperature:10 to 30°C

Humidity: 60%max.

- 10. Solder the enclosed capacitors within 168 hours after opening the moisture-proof package. After opening, store the capacitors in moisture-proof package with a desiccant and HIC card and keep the above condition.
- 11. In case the storage period has been exceeded 6 months or the indicator color of a enclosed HIC card has changed when the package has been opened, perform baking $(60^{\circ}\text{C} \times 168\text{hr})$ before soldering.

When the product is unpacked, the exposure time exceeds Floor time, the temperature and humidity around the product exceed the requirement. Reference condition for drying mounted or unmounted SMD packages (user bake: Floor life begins at time=0 after bake)

Level	Bake@40°C ≤5%RH	
	Saturated@30°C/85%RH	At limit of Floor life+72hr@30°C/60RH
3	79days	67days

■ Application

- 1. Ideal for use as X/Y capacitors for AC line filters and primary-secondary coupling on switching power supplies and AC adapters.
- 2. Ideal for use on D-A isolation and noise absorption for DAA modems without transformers.
- 3. Mounting Capacitor on both sides of PCB, increasing the space utilization ratio.

■ Part Number Designation

CT7 -250VAC - Y1 - B - 101 K O S

(1) (2) (3) (4) (5) (6) (7) (8)



	PART NO.	
From Molding SMD 250VAC-V1 con	Edition	Page
Epoxy Molding SMD 250VAC-Y1 cap	A	5

①Type

Code	Type Designation
CT7	Safety Standard Certified

3Class Code

Code	Class Code
Y1	Y1

⑤Capacitance

Code	Capacitance
101	100 pF
102	1000 pF

Shaping method

Code	Description
I	In-kink
0	Out-kink

②Rated Voltage

Code	Rated Vol. (AC)
250VAC	250V

4 Temperature Characteristic

GB	EIA	Temp. range	Cap. Change
В	Y5P	-25∼+85℃	±10%

6Tolerance

Code	Tolerance				
K	±10%				
М	± 20%				

®Lead Shape

Code	Shape			
S	SMD Type			

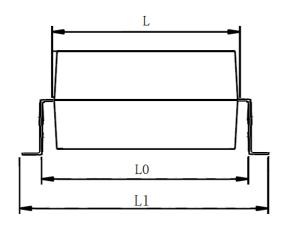
Part No.	CODE NO.	STYLE
	CT7-250VAC-Y1-B-101K OS	
	CT7-250VAC-Y1-B-221K OS	
	CT7-250VAC-Y1-B-331K OS	
	CT7-250VAC-Y1-B-471K OS	
	CT7-250VAC-Y1-E-102M OS	

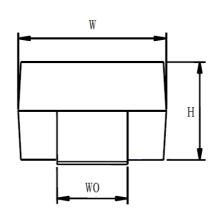


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Epoxy Molding SMD 250VAC-Y1 cap	A	6

■ Appearance and Dimension (Unit: mm)

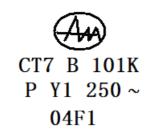
OS Series





Shaping method	L	W	Н	L0	L1	W0
os	6.2±0.3	5.2±0.3	2.40±0.15	8.4±0.3	10.0±0.3	2.5±0.2

■ Marking



€w)	Manufacturer's Marking
CT7	Type Designation
В	Temperature Characteristic
101	Nominal Capacitance
K	Capacitance Tolerance
P	Pb solder product
Y1	Class code
250~	Rated Voltage Mark
04F1	Manufactured Date Code (0: Year, 4: Month, F:
	date, 1: Sequence code)

■ Safety Certification

No	Certificate authority	Certificate No	Rated voltage
1	ENEC	40043423	400VAC-Y1/X1,250VAC-Y1/Y2/X1
2	VDE	40043423	400VAC-Y1/X1,250VAC-Y1/Y2/X1
3	UL	E232980	400VAC-Y1/X1,250VAC-Y1/Y2/X1
	KC	HU03028-15001A	250VAC-Y1

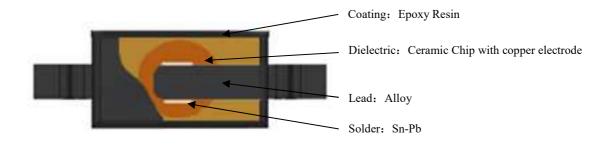
■ Exemption Clause

2010/571/EU 7(a): Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

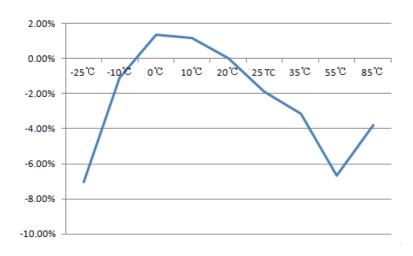


	PART NO.	
Energy Molding CMD 250VAC V1 con	Edition	Page
Epoxy Molding SMD 250VAC-Y1 cap	A	7

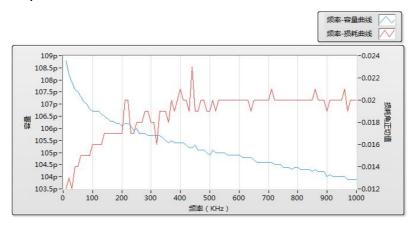
■ Structure



■ Temperature Characteristic Curve



■ Cap. & D.F.—Fre. Curve





Anshan Keifat Electronic Ceramic Technical Co., Ltd.							
					PART NO.		
Fnovy	Molding SN	/D 250VA	C-V1 can		Edition	Page	
Epoxy Molding SMD 250VAC-Y1 cap					А	8	
	Specification a						
	tem		pecifications		Test Metho	d	
1 Operating T		-40°C∼+12					
2 Appearance			or abnormalities	Visual inspection			
3 Dimensions			pecified dimensions		neasured by caliper		
Marking		To be easily		· ·	should be visually insp	pected.	
5 Capacitan	ice	In specified		Temp. 20°C ±2			
		Char.	Specifications	Vol. AC 5Vrm			
3 Dissipation	Factor(D.F.)/Q	B、E	≤2.5%		Freq. :1 \pm 0.1KHz,		
				The capacitance, dissipation factor should be measured 20°C with 1±0.1KHz and AC 5Vrms Max.			
				The insulation resistance should be measured wit			
				500±50V within 60±5 sec. of charging.			
7 Insulation F	Resistance (I.R.)	10000M Ω min		The voltage should be applied to the capacitor through a			
				resistor of 1M Ω .			
				The capacitor s	should not be damage	ed when the test	
		No failure		voltages from Table 1 are applied between the lead wires fo			
	Between Lead			60 sec.			
	Wires	Char.	Leakage current	ļ			
		B、E	1.0mA max.	<table 1=""></table>	Туре	Test Voltage	
				(Table 17	X1Y1	AC4000V(rms)	
				First, the termi	nals of the capacitor	should be connected	
				together, and t	he capacitor should b	e wrapped closely w	
				an aluminum fil	m around the body of	the capacitor to a	
) D: 1				distance about	${\bf 2}$ to ${\bf 3}{\bf m}{\bf m}$ from each	terminal. Then, put t	
B Dielectric				capacitor into t	the testing jig as show	vn in below figure.	
Strength				Finally, apply a	voltage of Table 2 fo	r 60 sec.	
					Test pin		
	Body	No failure	N. 6.7		Test pin		
	Insulation	ino fallure			Plastic	insulation	
				_	Alum	ninum film cladding	
					~		
					Туре	Test Voltage	

<Table 2>

X1Y1

AC4000V(r.m.s.)



	PART NO.	
Engres Molding CMD SEOVAC VI con	Edition	Page
Epoxy Molding SMD 250VAC-Y1 cap	A	9

T.			C	Took Mathaul					
Ito	em	-	Specifications	Test Method					
		Char.	Capacitance Change	The capacitance should be measured at each step as below					ep as below
9 Temperature C	Characteristic	B	±10%	table.					
		E	−56%∼+22%	Step	1	2	3	4	5
	Γ			Temp.(°C)	20±2	-25±2	20±2	85±2	20±2
				Solder the capac	itor to	the test	jig		Capacitor
				(glass epoxy board	d).		PCE		_ , ,
				The capacitor sho	uld be su	bjected to	a a	mmmm	1.6
10 Vibration				simple harmonic m	notion hav	ving a tota	ıl		
Resistance	Appearance	No mar	ked defect	amplitude of 1.5mr	m, the fre	quency be	eing varie	d uniforn	nly between
Resistance				the approximate li	mits of 10	0 to 55Hz.	The frequ	uency rai	nge, from 10
				to 55Hz and return	n to 10Hz	z, should b	e travers	ed in app	proximately
				1min.This motion s	should be	applied fo	or a perio	d of 2hrs	in each of 3
				mutually perpendicular directions (total of 6hrs.).					
				Immerse the capacitor in a solution of ethanol (JIS-K-8101) and					
		75% of the terminations are to be		rosin (JIS-K-5902) (25% rosin in weight proportion).					
11 Solder ability	of leads	soldered evenly and		Immerse in solder	solution	for 2 \pm 0.5	sec.		
		continuously.		Immersing speed: 25±2.5mm/s					
				Temp. of solder: 245±5°C Lead Free Solder (Sn-3.0Ag-0.5Cu)					
		No marked defect		Solder the capacitor to the test jig(glass epoxy board)shown in Fig.1					
			h	Then apply a force in the direction shown in Fig.1. The soldering					
			⁴	should be done us	J				
		7////	760 L V////////	care so that the soldering is uniform a free of defects such as heat					
				shock.					
			/// <u>*</u>		20	50 Pres	surizing		
12 Deflection	12 Deflection		100 t: 1.6	speed: 1.0mm/s					
				R230					
			Dimension(mm)	l l		7	Flexure.	ď	
		a	b c d		100-B	S-ABJ-T		53	
			11.7 2.7 1.0	Capacitance meter 45 45 (in mm)					
			· · · · · · · · · · · · · · · · · · ·		0- 7.5 0	Fig.1			
		1		1		1 1g. 1			



	PART NO.	
Engres Molding CMD SEOVAC VI con	Edition	Page
Epoxy Molding SMD 250VAC-Y1 cap	A	10

Item		:	Specifications		Test Method		
13 Adhesive Strength of Termination		No removal of the terminations or other defect should occur.		in F The sold con-	Solder the capacitor to the test jig(glass epoxy board)shown in Fig.2 Then apply 10N force in the direction of the arrow. The soldering should be done using reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock. Fig. 2		
	Appearance	No marked	defect	Prel	Preheat the capacitor as in		Capacitor
	Capacitance	Char.	Capacitance Change			he capacitor in t 260±5℃for	Molten Solder
	Change	B	±10% ±15%		± 1 sec. Let s		
	I.R.	1000MΩ n			condition for 24 ± 2 hrs., then measured. Immersing speed: 25 ± 2.5 mm/s		
14 Resistance to	1.1 \.	1000141 22 11	1111				
Soldering				Pre	etreatment for	r Y5P、Y5U char.	
Heat				Per	rform a heat t	reatment at 150 $^{+0}_{-10}$ °C for	60±5 min. and
	Dielectric _				then let sit for 24±2 hrs. at room condition.		
Strength		Per Item 8.		Prel	eheating		
					Step	Temperature	Time
					1	100 to 120℃	1 min.
					2	170 to 200 $℃$	1 min.



	PART NO.	
Engry Molding CMD 250VAC_V1 con	Edition	Page
Epoxy Molding SMD 250VAC-Y1 cap	A	11

Ite	m	S	pecifications	Test Method
	Appearance	No marked	defect	Before this test, the test shown in the following is
	Capacitance Change	Char. B E	# 10% # 15%	 Performed. Item 12 Deflection Item 13 Adhesive Strength of Termination (applied force
15 Humidity (under	D.F./Q	Char.	Specifications ≤5.0%	is 5N) Set the capacitor for 500^{+24}_{-0} hrs. at $40\pm2^{\circ}$ C in 90 to 95% relative humidity .
Steady State)	I.R.	3000MΩ m	nin	Pretreatment for Y5P、Y5U char.
	Dielectric Strength	Per Item 8.		Perform a heat treatment at 150^{+0}_{-10} °C for 60 ± 5 min. and then let sit for 24 ± 2 hrs. at room condition. Post-treatment: The capacitor should be stored for 1 to 2 hours at room condition.
16 Humidity	Appearance	No	marked defect	Before this test, the test shown in the following is
Loading	Capacitance Change	Char. B E	#10% ±15%	Performed. Item 12 Deflection Item 13 Adhesive Strength of Termination (applied force
	D.F./Q	Char.	Specifications ≤5.0%	is 5N) Apply the rated voltage for 500^{+24}_{-0} hrs. at $40\pm2^{\circ}$ C in 90% to 95% relative humidity .
	I.R.	3000 MΩ r	min	Pretreatment for Y5P、Y5U char.
	Dielectric Strength	Per Item 8.		Perform a heat treatment at 150^{+0}_{-10} °C for 60 ± 5 min. and then let sit for 24 ± 2 hrs. at room condition. Post-treatment: Capacitor should be stored for 24 ± 2 hrs. at room condition



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Epoxy Molding SMD 250VAC-Y1 cap	A	12

			Α	12			
I	Item		Specifications		Test Method		
	Appearance Capacitance Change	Char. B E	Capacitance Change ±20%	performed. • Item 12 Defl	ection	n in the following is	
17 Life	I.R. Dielectric Strength	Per Item		is 5N) Impulse voltage Each individual (X1Y2) / 8KV (Compacitors are and another individual) (X1Y2) / 8KV (Compacitors are another individual) (X1Y2) / 8KV (Compacitors are another individual) (Yange of the individual) (Yange	capacitor should be X1Y1) impulse for the applied to life test. T ₁ =1.2 ₁ T ₂ =50µ of 170% of rated voludiage is increased to hrs., at 125 ⁺² ₋₀ °C and or Y5P、Y5U char. treatment at 150 ⁺⁰ ₋₁₀ 24±2 hrs. at room of the column of th	ree times. Then the us=1.67T s ltage except that once o AC1000V (r.m.s.) for ad relative humidity of °C for 60±5 min. and condition. ± 2 hrs at room	
18 Passive Flammability		exceed 30	g time should not sec. paper should not ignite.	position that be only be exposed flame: 30 sec. Length of flame Gas burner: L In	est promotes burning d once to the flame. e: 12±1mm ength 35mm min. uside Dia. 0.5±0.1mm utside Dia. 0.9mm m s Purity 95% min.		



	PART NO.	
Engra Molding CMD 250VAC V1 con	Edition	Page
Epoxy Molding SMD 250VAC-Y1 cap	Α	13

Item	Specifications	Test Method
19 Active Flammability	The cheesecloth should not be on fire.	The capacitor should be individually wrapped in at least one but not more than two complete layers of cheesecloth. The capacitor should be subjected to 20 discharges. The interval between successive discharges should be 5 sec. The U_{AC} should be maintained for 2 min. after the last discharge. $C_{1,2}: 1\mu F \pm 10\% \qquad C_3: 0.033 \mu F \pm 5\% \ 10 kV$ L1 to $4: 1.5 mH \pm 20\% \ 16 A$ Rod core choke Ct: $3\mu F \pm 5\% \ 10 kV$ R: $100\Omega \pm 2\%$ Cx: Capacitor under test $U_{AC}: U_R \pm 5\%$ F: Fuse, Rated $10A$ $U_R: Rated Voltage$ Ut: Voltage applied to Ct



	PART NO.	
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Epoxy Molding SMD 250VAC-Y1 cap	A	14

<u>Ite</u> m		Sp	pecifications	Test Method			
	Appearance	No marked defect		The capacitor should be subjected to 5 temperature			to 5 temperature
			Char. Capacitance Change		then con	secutively to 2 imn	nersion cycles.
	Capacitance	В	±10%			< Temperature (Cycle>
	Change	Е	±20%		Step	Temperature($^{\circ}$ C)	Time(min)
	D. F. (0)	Char.	Specifications] -	1	-40+0/-3	30
	D.F./Q	B, E	≤5.0%	-	2	Room temp.	3
	I.R.	3000M Ω mi	n] .	3	125+3/-0	30
				1 .	4	Room temp.	3
				<immersion cycle=""></immersion>			
21 Temperature				Step	Temp.(°C) Time(min)	Immersion Water
and immersion				1	65+5/	-0 15	Clean water
Cycle				2	0±3	3 15	Salt water
			Cycle time:2 cycles				
	Dielectric			Pre-tre	atment:		
	Strength	Per Item 8.		Capacitor should be stored at $85\pm2^{\circ}$ C for 1 h		2° C for 1 hr., then,	
	Strength		placed at room condition for 24±2 hrs.				
				Pretreatment for Y5P、Y5U char.			
			Perform a heat treatment at 150^{+0}_{-10} °C for 60 ± 5 min. an				
				then let sit for 24±2 hrs. at room condition.			
				Post-tr	eatment:		
				Capacit	or should	d be stored for 24±	2 hrs. , at room
				conditio	n.		



	PART NO.	
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Epoxy Molding SMD 250VAC-Y1 cap	Α	15

■ Package

Paste product label and moisture-sensitive warning label on the taping reel, then, take the reel, HIC card and desiccant(30g) into the package bag, vacuum sealed.

Product Label



No.	Description	No.	Description
1	Code Number	5	Remark
2	ITEM	6	Check
3	SPEC	7	Produce Date
4	Quantity	8	Batch

Package style and moisture-sensitive warning label Label



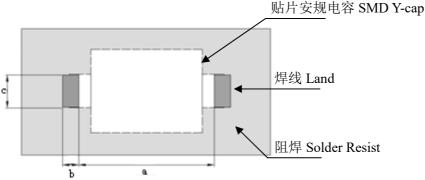
警告:虚度敏感产品 Caution:moisture-sensitive devices Level 3			
储存条件 Storage Condition	Temperature: 10 to 30°C Humidity: 60%max.		
使用期限 Using Period	6个月 6months		
打开包装后使用条件 Using Condition after opening	打开包装后室内环境30℃/60%RH,168小时内回流焊接 未使用产品附干燥剂和HIC卡密封包装储存 Mounted & Reflow within 168hr of factory condition ≤30℃/60%RH Stored in moisture-proof package with a desiccant and HIC card		
后处理 Post-treatment	如果超过6个月的储存期,或包装打开后随附的HIC 卡的指示颜色发生变化,则应在焊接前进行烘烤 (60℃x168hr)。 In case the storage period has been exceeded 6 months or the color of HIC card has changed, perform baking (60℃x168hr)before soldering.		



	PART NO.	
Energy Molding CMD 250VAC_V1 con	Edition	Page
Epoxy Molding SMD 250VAC-Y1 cap	A	16

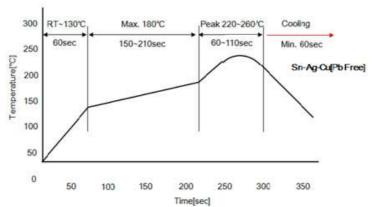
■ Recommended Soldering Condition

1. Soldering Land Pattern Size



Shaping method	а	b	С
os	8.4 ± 0.3 mm	0.9 ± 0.1 mm	2.6±0.1mm

2. Reflow Soldering Temperature Profile



	Zone	Temp. range (℃)	Time(sec)	Remark
а	Curing	RT~130	60	
b	Preheat	180 max	150~210	Solder: Sn-Ag-Cu
С	Soldering	220~260(260 max)	60~110	Peak time: less than 10 sec
d	Cooling	220~RT	60 min	

Solder ability of tin plating termination pins might be deteriorated when a low temperature soldering profile where the peak solder temperature is below the melting point of tin is used. Please confirm the solder ability of tin plated termination pins before use

The maximum temperature in the air outlet and the space of Reflow soldering is 280°C max., if the temperature exceed, it maybe a failure occur. Our company will not be held responsible for any adverse effects caused by over temperature using

■ Caution (Rating)

1. Operating Voltage

When DC-rated capacitors are to be used in AC or ripple current circuits, be sure to maintain the V p-p value of the applied voltage or the Vo-p that contains DC bias within the rated voltage range.



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Epoxy Molding SMD 250VAC-Y1 cap	A	17

When the voltage is applied to the circuit, starting or stopping may generate irregular voltage for a transit period because of resonance or switching. Be sure to use a capacitor with a rated voltage range that includes these irregular voltages.

Voltage	DC Voltage	DC+AC Voltage	AC Voltage	Pulse Voltage (1)	Pulse Voltage (2)
Positional Measurement	Vo-p	Vo-p	V _{p-p}	V _P -p	Vp-p

2. Operating Temperature and Self-generated Heat (Apply to B/E Char.)

Keep the surface temperature of a capacitor below the upper limit of its rated operating temperature range. Be sure to take into account the heat generated by the capacitor itself. When the capacitor is used in a high-frequency current, pulse current or similar current, it may have self-generated heat due to dielectric loss. Applied voltage load should be such that self-generated heat is within 20° C under the condition where the capacitor is subjected to an atmospheric temperature of 25° C. When measuring, use a thermocouple of small thermal capacity-K of Φ 0.1mm under conditions where the capacitor is not affected by radiant heat from other components or wind from surroundings. Excessive heat may lead to deterioration of the capacitor's characteristics and reliability. (Never attempt to perform measurement with the cooling fan running. Otherwise, accurate measurement cannot be ensured.)

3. Test Condition for Withstanding Voltage

(1) Test Equipment

Test equipment for AC withstanding voltage should be used with the performance of the wave similar to 50/60Hz sine wave.

If the distorted sine wave or overload exceeding the specified voltage value is applied, a defect may be caused.

(2) Voltage Applied Method

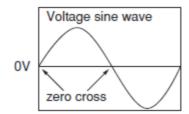
When the withstanding voltage is applied, the capacitor's lead or terminal should be firmly connected to the output of the withstanding voltage test equipment, and then the voltage should be raised from near zero to the test voltage.

If the test voltage without the raise from near zero voltage would be applied directly to capacitor, test voltage should be applied with the zero cross.* At the end of the test time, the test voltage should be reduced to near zero, and then capacitor's lead or terminal should be taken off the output of the withstanding voltage test equipment. If the test voltage without the raise from near zero voltage would be applied directly to capacitor, the surge voltage may rise, and therefore, a defect may be caused.



	PART NO.	
From Molding CMD 250VAC-V1 cor	Edition	Page
Epoxy Molding SMD 250VAC-Y1 cap	Α	18

*ZERO CROSS is the point where voltage sine wave passes 0V. See the figure at below.



4. Fail-Safe

When the capacitor is broken, failure may result in a short circuit. Be sure to provide an appropriate fail-safe function like a fuse on your product if failure could result in an electric shock, fire or fuming.

FAILURE TO FOLLOW THE ABOVE CAUTIONS MAY RESULT, WORST CASE, IN A SHORT CIRCUIT AND CAUSE FUMING OR PARTIAL DISPERSION WHEN THE PRODUCT IS USED.

Caution (Storage and Operating Condition)

The insulating Epoxy molded capacitors does not form a perfect seal; therefore, do not use or store capacitors in a corrosive atmosphere, especially where chloride gas, sulfide gas, acid, alkali, salt or the like are present. And avoid exposure to moisture. Before cleaning, bonding or molding this product, verify that these processes do not affect produce quality by testing the performance of a cleaned, bonded or molded product in the intended equipment.

This one is MSL 3 product. So, in order to avoid the absorption of moisture, capacitors are packed in moisture-proof envelope.

Store the capacitors in the following conditions at all times, and use within 6 months after delivered.

Temperature:10 to 30°C

Humidity: 60%max.

Solder the enclosed capacitors within 168 hours after opening the moisture-proof package. After opening, store the capacitors in moisture-proof package with a desiccant and HIC card and keep the above condition.

In case the storage period has been exceeded 6 months or the indicator color of a enclosed HIC card has changed when the package has been opened, perform baking (60°Cx168hr)before soldering.

When the product is unpacked, the exposure time exceeds Floor time, the temperature and humidity around the product exceed the requirement. Reference condition for drying mounted or unmounted SMD packages (user bake: Floor life begins at time=0 after bake)



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Level	Bake@40°C ≤5%RH		
	Saturated@30°C/85%RH	At limit of Floor life+72hr@30°C/60RH	
3	79days	67days	

FAILURE TO FOLLOW THE ABOVE CAUTIONS MAY RESULT, WORST CASE, IN A SHOCT CIRCUIT AND CAUSE FUMING OR PARTIAL DISPERSION WHEN THE PRODUCT IS USED.

Caution (Soldering, Mounting and Handing)

1. Vibration and Impact

Do not expose a capacitor or its pins to excessive shock or vibration during use.

Excessive shock or vibration may cause fatigue destruction of lead wires mounted on the circuit board.

Please take measures to hold a capacitor on the circuit boards by adhesive, molding resin or another coating.

Please confirm there is no influence of holding measures on the product with the intended equipment.

2. Soldering

When soldering this product to a PCB/PWB, do not exceed the solder heat resistance specifications of the capacitor. Subjecting this product to excessive heating could melt the internal junction solder and may result in thermal shocks that can crack the ceramic element.

Soldering the capacitor with a soldering iron should be performed in the following conditions.

Temperature of iron-tip: 400 degrees C. max.

Soldering iron wattage: 50W max.

Soldering time: 3.5 sec. max.

3. Bonding, Resin Molding and Coating

Before bonding, molding or coating this product, verify that these processes do not affect the quality of capacitor by testing the performance of the bonded, molded or coated product in the intended equipment.

In case the amount of applications, dryness/hardening conditions of adhesives and molding resins containing organic solvents (ethyl acetate, methyl ethyl ketone, toluene, etc.) are unsuitable, the outer coating resin of a capacitor is damaged by the organic solvents and it may result, worst case, in a short circuit.

The variation in thickness of adhesive, molding resin or coating may cause outer coating resin cracking and/or ceramic element cracking of a capacitor in a temperature cycling.

4. Treatment after Bonding, Resin Molding and Coating

When the outer coating is hot (over 100 degrees C.) after soldering, it becomes soft and fragile. Therefore, please be careful not to give it mechanical stress.

FAILURE TO FOLLOW THE ABOVE CAUTIONS MAY RESULT, WORST CASE, IN A SHOCT CIRCUIT AND CAUSE FUMING OR PARTIAL DISPERSION WHEN THE PRODUCT IS USED.



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Notice (Soldering and Mounting)

Cleaning (ultrasonic cleaning)

To perform ultrasonic cleaning, observe the following conditions.

Rinse bath capacity: Output of 20 watts per liter or less. Rinsing time: 5 min. max.

Do not vibrate the PCB/PWB directly. Excessive ultrasonic cleaning may lead to fatigue destruction of the pins.

Notice (Rating)

- 1. Capacitance Change of Capacitors
- (1) For B/E char.

Capacitors have an aging characteristic, whereby the capacitor continually decreases its capacitance slightly if the capacitor is left on for a long time. Moreover, capacitance might change greatly depending on the surrounding temperature or an applied voltage. Therefore, it is not likely to be suitable for use in a constant time circuit.

Please contact us if you need detailed information.

2. Performance Check by Equipment

Before using a capacitor, check that there is no problem in the equipment's performance and the specifications.

Generally speaking, CLASS 2 (B/E char.) ceramic capacitors have voltage dependence characteristics and temperature dependence characteristics in capacitance, so the capacitance value may change depending on the operating condition in the equipment. Therefore, be sure to confirm the apparatus performance of receiving influence in the capacitance value change of a capacitor, such as leakage current and noise suppression characteristic.

Moreover, check the surge-proof ability of a capacitor in the equipment, if needed, because the surge voltage may exceed specific value by the inductance of the circuit.